

AMENDMENTS TO THE SPECIFICATION:

Please amend the Specification as follows:

On page 19, please replace the first full paragraph that begins "In the semiconductor apparatus..." with the following paragraph:

In the semiconductor apparatus for fingerprint recognition of the second embodiment, the static-electricity drawing wiring having a thickness of about 2 μm has a structure such that it protrudes from the fingerprint-recognizing surface upwardly, as compared to the electrode having a thickness of about 0.5 μm , and, in addition, the static-electricity drawing wiring is exposed to the outside through the surface of the semiconductor apparatus for fingerprint recognition. Therefore, when a finger or any other material which is electrostatically charged is brought closer to the fingerprint-recognizing surface, the static electricity is not discharged into the electrode but into the static-electricity drawing wiring. (The effect of drawing static electricity in the second embodiment is larger than that in the first embodiment by a magnitude corresponding to the fact that the static-electricity drawing wiring is exposed to the outside through the surface of the semiconductor apparatus for fingerprint recognition.)